

Title	PCB Specification
Document Name	PCOREBBBULP_REV130_pcbspec.docx
Revision	1.30
Subject	PicoCoreBBULP
Author	MD

1	General PCB Specification	2
2	Data Information	3
3	Layer Sequence	4
4	Panel creation	5

Revision History

Revision	Date (dd.mm.yy)	Author	Changes
1.30	14.10.2019	MD	created; Initial release

1 General PCB Specification

	Value	Unit	Notes
Project	PicoCOREBBULP		
PCB Revision	1.30		PICOCOREBBULP-REV130-GERBER.zip
Product Type	Baseboard		

No. of Layers	6		
Material	FR-4		IPC 4101
Board Type	6 Multilayer		Plated Through Hole
Glass Transition Temperature Tg	150	°C	
Cu Weight/Thickness Outers/Inners	35 / 35	µm	
PCB Length	100 ± 0.1	mm	
PCB Width	72 ± 0.1	mm	Made as panel 2x1 110x144 mm
PCB Thickness (finished)	1.59 ± 0.1	mm	
Total No Holes	598		
Total No µHoles	0		
Solder Resist (Side1,2,Both)	both		
Solder Resist Color	green		
Silk Screen (1, 2, both, none)	none		
Silk Screen Color	none		
Approval	UL		94V-0 UL rating or better UL sign shall be marked on the solder or component side in either etch or ink
RoHS	Directive 2002/95/EC		
PCB Complies to Specification	IPC 6011 IPC 6012		

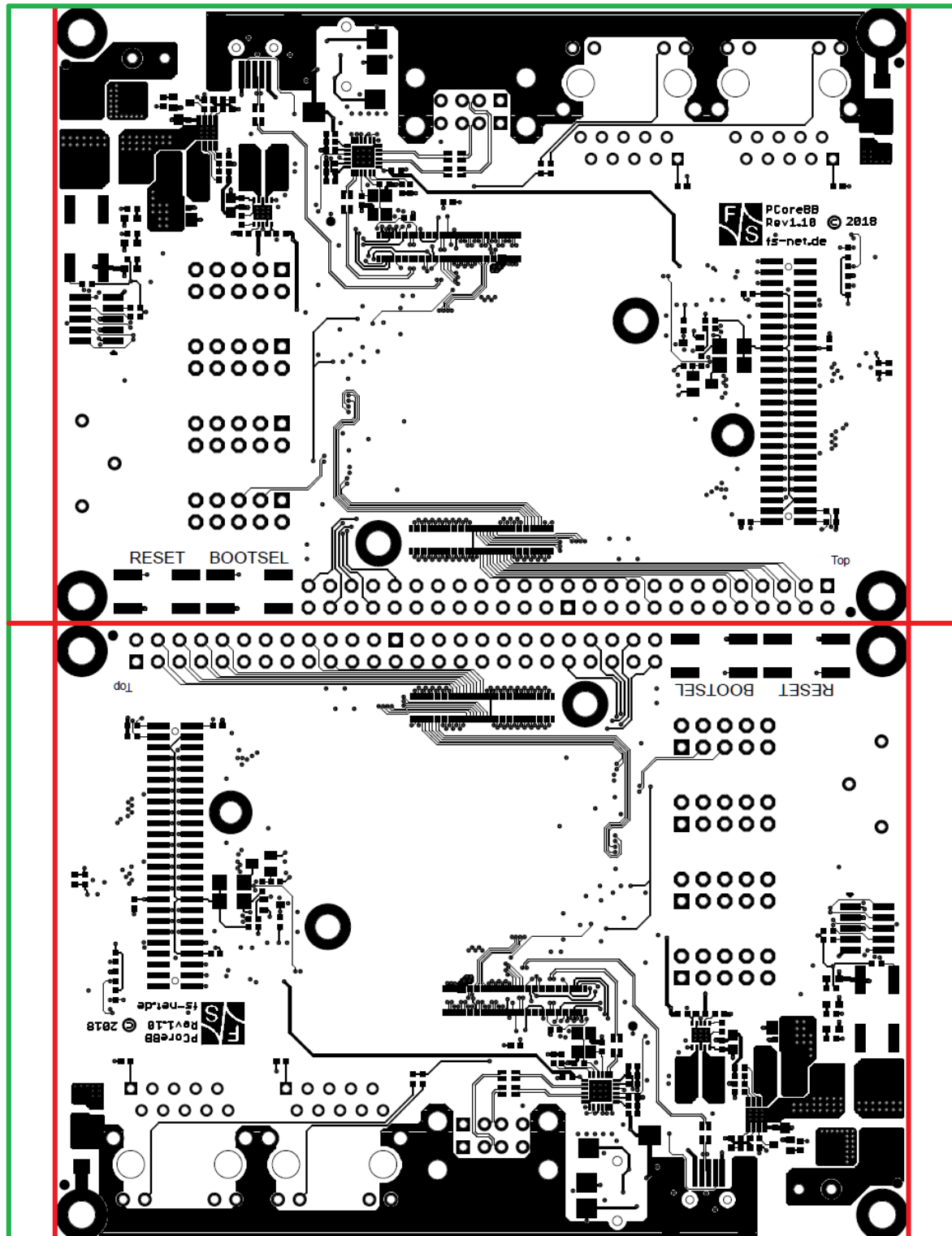
2 Data Information


	Format	Notes
Gerber File	RS274-X: 2.6 Leading Abs Inch	packed in file PICOCOREBBULP-REV130-GERBER.zip
Drill File	NC Drill, Excellon, Format 2.5	packed in file PICOCOREBBULP-REV130-GERBER.zip

3 Layer Sequence

Layer	Name	Notes
1	Top layer	picocoremx7ulpbb-panel-top.gtl
2	INT1	picocoremx7ulpbb-panel-int1.gp1
3	INT2	picocoremx7ulpbb-panel-int2.gp1
4	INT3	picocoremx7ulpbb-panel-int3.gp1
5	INT4	picocoremx7ulpbb-panel-int4.gp1
6	Bottom layer	picocoremx7ulpbb-panel-bottom.gbl

4 Panel creation



 Scoring

 Milling